

**SOLDERING DEVICE AND METHOD FOR PRODUCING A SOLDER CONNECTION,
USING BASE AND PRESSURE PLATES AND A STOP DEVICE**

Abstract

A soldering apparatus (50, 150, 250) is proposed for producing a solder connection between a plurality of components (12A, 12B) by heating and melting solder material (16) which is arranged between the components (12A, 12B) to be connected, and/or for coating a component with solder material (16), comprising a base plate (66) and a pressure plate (64), between which a solder group (10) comprising the component(s) (12A, 12B) and the solder material (16) is received, and which are adjustable relative to one another with regard to the spacing thereof for exerting a pressure force on the solder group (10).

It is proposed that a stop apparatus is provided which limits the spacing between the base plate (66) and the pressure plate (64) to a minimum spacing such that, once the solder material (16) has melted, the solder group (10) has a predetermined thickness.

A secondary aspect proposes a connection method in which, prior to application of a pressure force, the components (12A, 12B) to be connected are initially provisionally connected with a solid or pasty bonding material (18) to form a solder group (10) in which the components (12A, 12B) are fixed relative to one another in a joining position.

[Fig. 6]